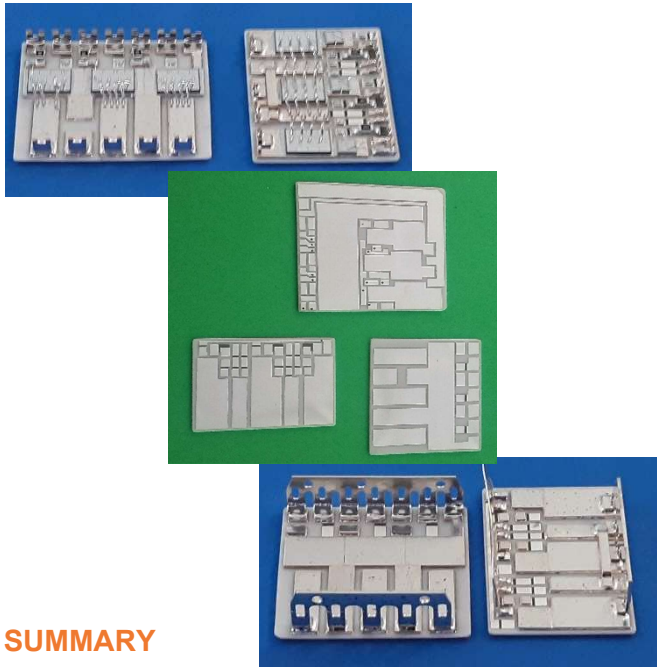




Composite Modules Inc.

High-Powered Hybrid Microelectronics



- Metalized Ceramic Substrates for Power Handling Circuits
- Dimensions from 0.050in² - 2.5 in²
- 96% Alumina Technical Ceramic, Electroless Silver, and Tungsten Metalization
- Applicable Markets: Aviation, Military/Defense

Case Study 1-Standard Power Plane for Motor Controller

- Up to 80A
- Bare Die Attachment
- Board size <2.5in²
- Proprietary Heat Spreader Utilized for Passive Cooling
- Designed for Harsh Environments

Case Study 2-Customized Power Plane

- Up to 60A
- Bare Die Attachment
- 20 to 125C Operating Temperature Range
- Proprietary Heat Spreader Utilized for Passive Cooling
- Designed for Hermetic Packaging

SUMMARY

CMI offers customers the flexibility to manufacture a product that meets their design criteria or select/modify a high-powered hybrid microelectronic from CMI.

Our Engineering expertise ranges from Design for Manufacture to the development of a bottom up design for populated power handling ceramics and single component substrate hybrid microelectronics.

CMI strives to meet passive heat dissipation and matched CTLE to enable components to perform at maximum levels while extending the life cycle by using our proprietary material and heat sinks.

ABOUT US

Our story is a long one and while the years have brought many changes, from our company name to our industry, we have never faltered in our mission to deliver highly designed and performing custom solutions.

We began as Joburn Tool in 1966 in Attleboro, Massachusetts working in the tool and die business before taking the steps toward manufacturing semiconductor packaging materials for the electronics industry as Composite Technical Alloys. After decades in the industry, we created Composite Modules, Inc. which was followed by the creation of our sister company, Composite Motors, Inc.

Since 1965, we have been committed to delivering high quality and high precision electronic products for extreme environments. Composite Motors has met the continuous demand from industry leaders for smaller size, greater functionality, and innovative electronic devices that operate in harsh environments.